ULTRA·REL[®] Ceramic Hermetic **Frequency Mixers**

300 MHz to 12 GHz LO Levels 4 to 17 dBm

The Big Deal

- 3-Year Guarantee
- Hermetically sealed LTCC construction
- Low-profile case, 0.06" high
- Priced for outstanding VALUE

Product Overview

Mini-Circuits MAC mixers employ a unique new design and a highly repeatable, tightly controlled, automated process that delivers industry-leading reliability at a remarkably affordable price. Schottky diode quads meeting our strict specifications are bonded to a multilayer integrated LTCC substrate, and then hermetically sealed under a controlled atmosphere with gold-plated covers and eutectic AuSn solder. These passive, doublebalanced mixers have been tested to MIL requirements for gross leak, fine leak, thermal shock, vibration, acceleration, mechanical shock, and HTOL, and every MAC mixer is backed with our 3-year guarantee.

Click here for more about the MAC mixer

Feature	Advantages
Low, Flat Conversion Loss	No need to compensate for variations over frequency.
Hermetically Sealed	Ideal for use anywhere long-term reliability adds bottom-line value: high moisture areas, busy production lines, high-speed distribution centers, heavy industry, outdoor settings, and unmanned facilities, as well as military applications.
Rugged LTCC/Hermetic Construction	Demonstrated reliability in harsh, physically abusive environments with high vibration, ac- celeration, and/or mechanical shock.
Wide Operating Temperature Range	Guaranteed performance from -55 to +125°C. MAC mixers have also passed thermal shock testing from -55 to +150°C, through 1000 cycles, 15 minutes per cycle.
Exposed Termination Ends	Our unique case design allows for easy visual inspection of side solder fillets per IPC- A-610 section 8.3.4.6, and features gold-plated terminations for excellent solderability.
Incredible Performance/Price	Game-changing affordability brings Hi-Rel hermetic mixers within the reach of commer- cial budgets.

Key Features



CASE STYLE: DZ1650

Notes

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MAC Series

Ceramic, Hermetically Sealed Frequency Mixer wide BAND

Level 7 (LO Power+7 dBm) 3800 to 12000 MHz

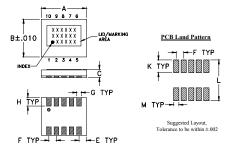
Maximum Ratings

Operating Temperature	-55°C to 125°C		
Storage Temperature	-65°C to 150°C		
RF Power	50 mW		
IF Current	40 mA		
Permanent damage may occur if any of these limits are exceeded.			

Pin Connections

LO	10
RF	5
IF	3
GROUND	1,2,4,6,7,8,9

Outline Drawing



Outline Dimensions (inch)

D

L

270

6.86

Demo Board MCL P/N: TB-956+ Suggested PCB Layout (PL-045)

Е

.050

1.27

035

0.89

Μ

PACKAGE OUTLINE

.226 2 PL

_17 X Ø.015 PTH FOR GROUND

F

.050

1.27

G

.030

0.76

grams

0.29

wt

С

.060

1.52

085

2.16

Κ

Features

- wide bandwidth, 3800 to 12000 MHz
- · low conversion loss, 6.0 dB typ.
- LTCC double balanced mixer
- · aqueous washable
- low cost
- low profile, 0.060"
- protected by US Patent 7,027,795 <u>3-YEAR GUARANTEE - The Most Reliable Mixers</u>

Applications

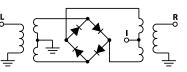
- satellite up and down converters
- line of sight links
- defense radar
- defense communications federal fixed service
- Electrical Specifications at 25°C Condition (MHz) Min Parameter Max Units Typ. Frequency Range, LO/RF 3800 - 12000 MHz Frequency Range, IF DC - 1800 MHz 3800 - 6500 7.7 5.6 6500 - 9500 Conversion Loss' 5.9 8.2 dB 9500 - 12000 6.0 8.2 22 3800 - 6500 32 LO to RF Isolation 6500 - 9500 27 38 _ dB 9500 - 12000 18 26 3800 - 6500 8 13 LO to IF Isolation 6500 - 9500 28 39 _ dB 9500 - 12000 14 23 3800 - 6500 10 _ IP3 6500 - 9500 _ 7 dBm 9500 - 12000 10 RF Input Power at 1 dB Compression dBm +1

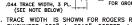
*Conversion Loss measured at 30 MHz IE

Typical Performance Data at 25°C and LO=+7dBm

Freq (N	uency IHz)	Conversion Loss (dB)	Isolation L-R (dB)	Isolation L-I (dB)	VSWR RF Port (:1)	VSWR LO Port (:1)
RF	LO	LO +7dBm	LO +7dBm	LO +7dBm	LO +7dBm	LO +7dBm
	20	17 dBill	17 dBill	17 dBill	17 dBill	17 dBill
3800.1	3830.1	5.99	31.07	10.00	1.91	2.94
4200.1	4230.1	5.27	30.81	11.42	1.75	2.96
4600.1	4630.1	5.04	26.94	12.37	1.62	3.01
5000.1	5030.1	4.87	29.19	12.85	1.74	3.04
5400.1	5430.1	6.00	28.42	14.42	2.30	3.07
5800.1	5830.1	6.41	23.66	17.11	1.62	3.11
6200.1	6230.1	5.42	27.88	23.68	1.27	3.48
6600.1	6630.1	5.21	33.16	30.31	1.16	3.58
7000.1	7030.1	6.24	35.43	35.14	1.96	3.49
7400.1	7430.1	5.63	37.74	37.00	2.13	3.20
7800.1	7830.1	5.46	38.95	37.21	2.50	2.56
8200.1	8230.1	5.90	38.84	39.61	2.83	1.83
8600.1	8630.1	6.44	34.18	43.03	3.20	1.73
9000.1	9030.1	6.57	38.49	48.65	3.02	1.88
9400.1	9430.1	5.86	34.37	40.17	2.71	2.35
9800.1	9830.1	5.58	30.24	30.03	2.37	2.72
10200.1	10230.1	5.70	30.90	19.19	1.69	2.90
10800.1	10830.1	5.58	24.14	22.91	1.18	2.38
11600.1	11630.1	6.16	21.85	28.95	1.65	1.40
12000.1	12030.1	6.38	24.79	23.67	1.96	1.59

Electrical Schematic





(SLE WOLE BELOW) NOTES: 1. TRACE WIDTH IS SHOWN FOR ROGERS RO43508 WITH DIELECTRIC THICKNESS .020" ± .0015"; COPPER: 1/2 02. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED. 2. BOTTOM SIDE OF THE PCB IS CONTINUIOUS GROUND PLANE. DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)

DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

Notes

A

.30

Н

7.62

056

1.42

B

J

050 | | .038

PIN 1

.250

6.35

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+RoHS Compliant The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications



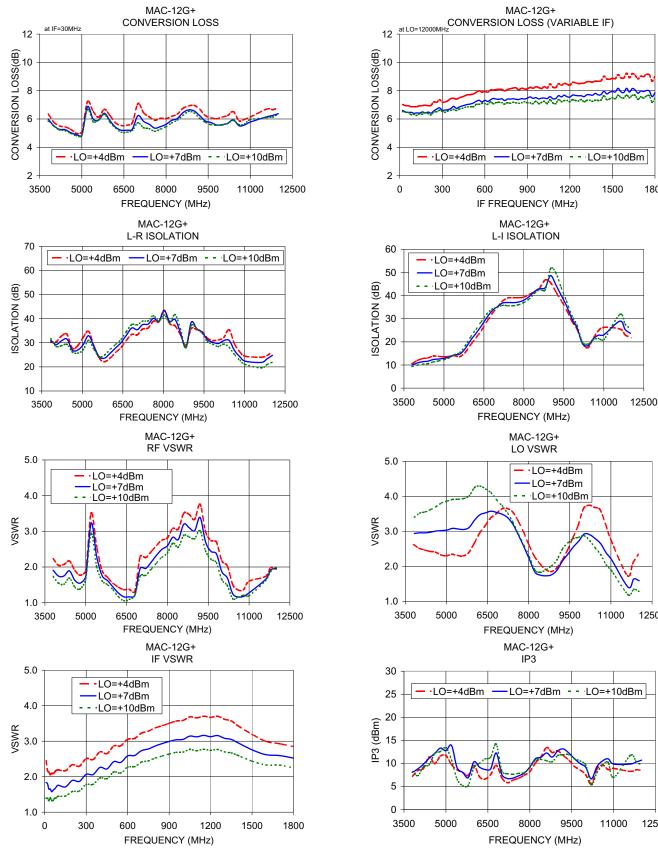
Performance Charts

MAC-12G+

1800

12500

12500



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Mini-Circuits

Designed and Built for Long-Term Reliability in **HOSTILE ENVIRONMENTS**



Mini-Circuits MAC mixers meet or exceed the following qualifications:

Gross Leak	MIL-STD-202 Method 112, Condition D (100% of all MAC Mixers we ship)
Fine Leak	MIL-STD-202 Method 112, Condition C, Procedure IIIa
Thermal Shock	MIL-STD-202 Method 107 (-55/+100C°, 1000 cycles, 15 minutes) (-55/+150C°, 1000 cycles, 15 minutes)
Vibration	MIL-STD-202 Method 204, Condition D (10-2000Hz sine, 20g, 3 axis, 12 c.y.ea.)
Acceleration	MIL- STD-883 Method 2001, Condition E
Mechanical Shock	MIL-STD-202 Method 213, Condition A
HTOL	MIL-STD-202 Method 108, Condition D (1000 hours, 125°C, at rated LO level)
Multiple Reflow	JESD22-B102
Bend Test	JESD22-B113
Adhesion Strength	Push test >10lb









All Photos courtesy of U.S. Military and NASA

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